

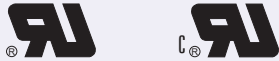


1600 Series AGP Card Edge Connector

.039 [1.00] Contact Centers

Specifications

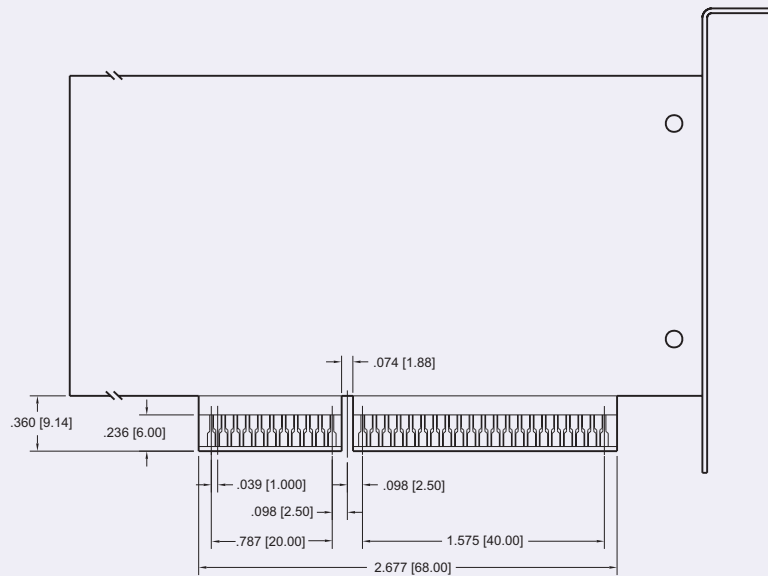
- Insulator Material: Glass-filled PCT, 94V-O Rated.
- Contact Material: Copper Alloy
- Current Rating: 1 Amp max.
- Voltage: 250 V AC
- Insulation Resistance: 800M Ω min.
- Dielectric Withstand Voltage: 400 V
- Voltage Drop: 30m volt at rated current
- Contact Resistance: 30m Ω max. at rate current
- Board Insertion Force to PCB: 15 lbs. max.
- Durability: 50 cycles
- Temperature: -55°C to +125°C



Recognized under the recognized component Program of Underwriters Laboratories, Inc.
File Numbers: E146967 and E176234

Features

- Used with Accelerated Graphics Cards
- Interconnect supports high performance 3D graphics and full motion video.
- Compatible with AGP 1X, 2X, and 4X
- Metal fork lock PCB retention
- Provides low card insertion force
- SMT process compatible

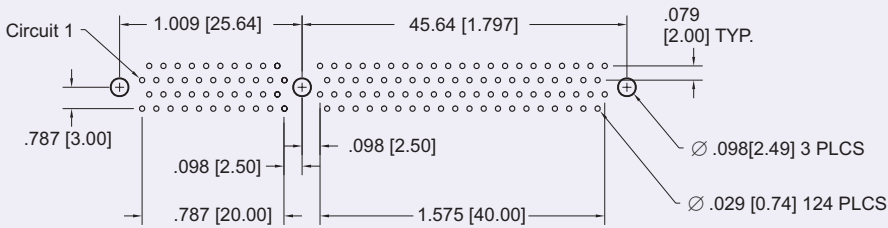
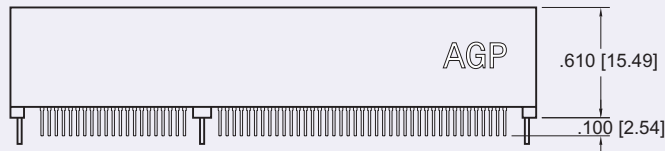
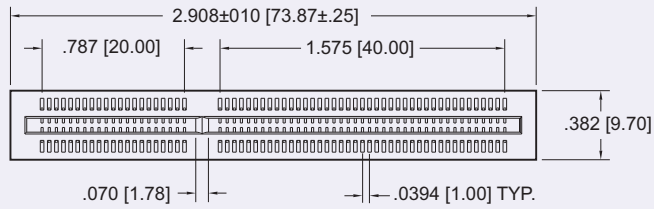
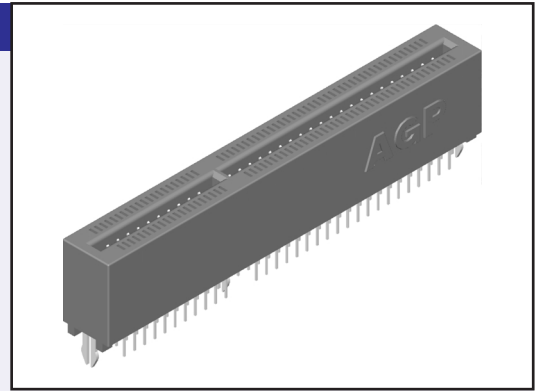


RECOMMENDED MODULE THICKNESS: .062 [1.57]

MOUNTING STYLE

1= Clearance Hole	2= #4-40 Threaded Insert	3= Flush Mount	4= Flush Mount / #4-40	5= No Mounting Ear	6= Side Mounting

.039 [0.99] Contact Centers, AGP Connector



PCB LAYOUT

Dimensions are in inch [mm]

PART NUMBERING



SERIES CODE

.039 [1.00] AGP Card Edge

NO. CONTACT PAIRS

31 (124 Circuit)

MOUNTING STYLE

- 1 = Clearance Hole
- 2 = #4-40 Threaded Insert
- 3 = Flush Mount
- 4 = Flush Mount / #4-40 Threaded Insert
- 5 = No Mounting Ears
- 6 = Side Mounting

CUSTOM VARIATION
CONSULT FACTORY

TERMINATION TYPE

- 1 = Staggered Dip Solder
- 2 = Right Angle (not shown)

PLATING

50µ" Nickel Underplate	
CONTACT	TAIL
01 = Flash Au	100µ" Sn
10 = 10µ" Au	100µ" Sn
20 = 15µ" Au	100µ" Sn
30 = 30µ" Au	100µ" Sn

CONSULT FACTORY FOR CONNECTORS BUILT TO YOUR SPECIFICATION